

**SED1023**

**Dual P-Channel Enhancement Mode Field Effect Transistor**

**General Description**

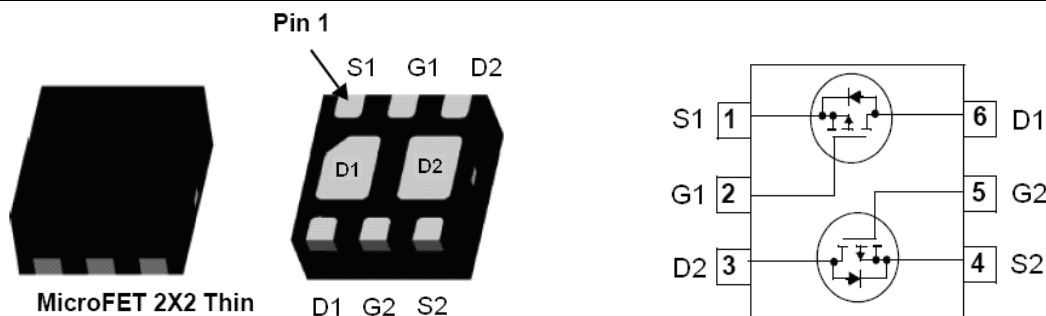
The SED1023 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge.

**Features**

$V_{DS}(V) = -20V$

$R_{DS(ON)} < 60m\Omega (V_{GS} = -4.5V @ I_D = -4.7A)$

$R_{DS(ON)} < 100m\Omega (V_{GS} = -2.5V @ I_D = -1.0A)$



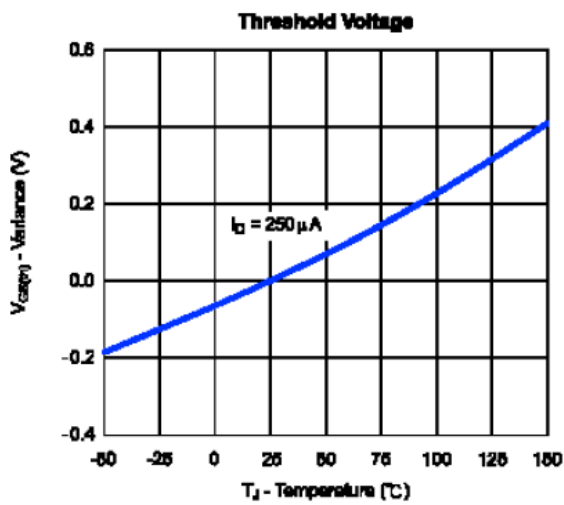
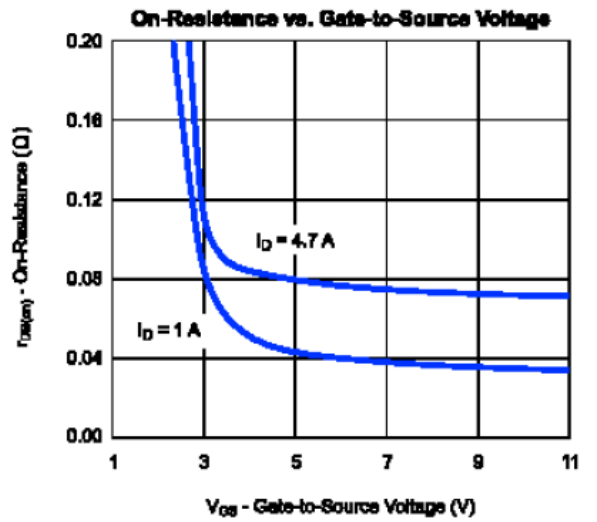
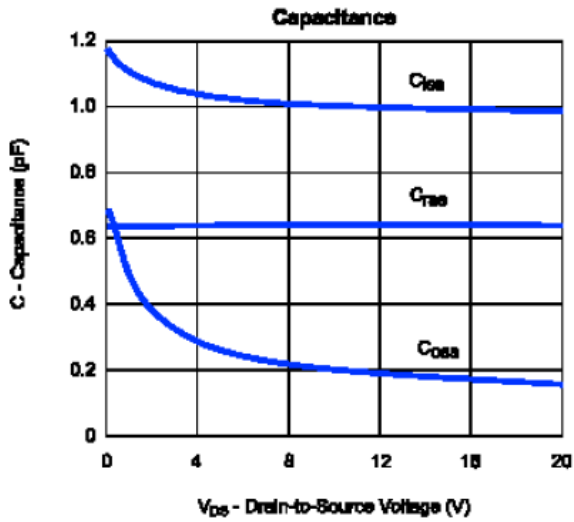
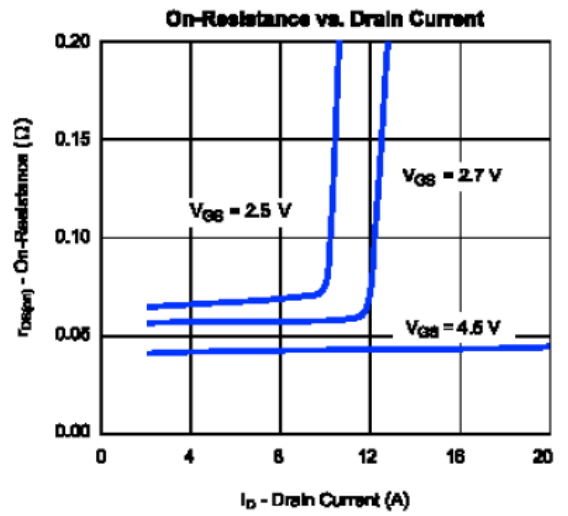
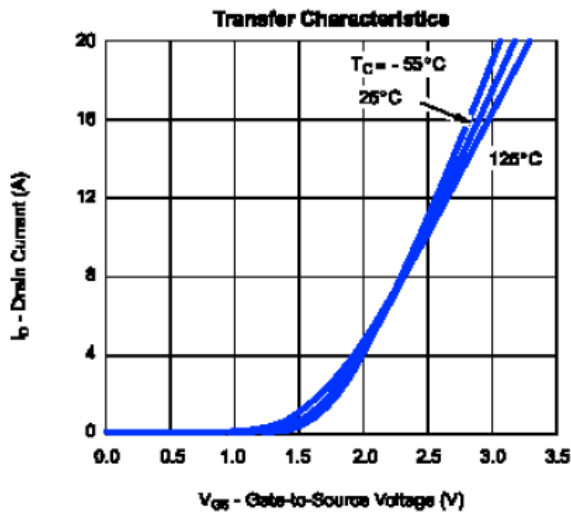
**Absolute maximum ratings (Ta=25°C)**

Parameter	Symbol	MOSFET1	MOSFET2	Unit
Drain-Source Voltage	$V_{DS}$	-20	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$T_A = 25^\circ C$	$I_D$	-4.2	A
Pulsed Drain Current <sup>B</sup>				
Power Dissipation	$T_A = 25^\circ C$	$P_D$	1.5	W
	$T_A = 70^\circ C$		0.7	
Junction and Storage Temperature Rang	$I_J, I_{STG}$	-55 to 150	-55 to 150	$^\circ C$

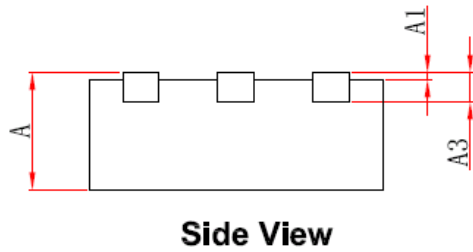
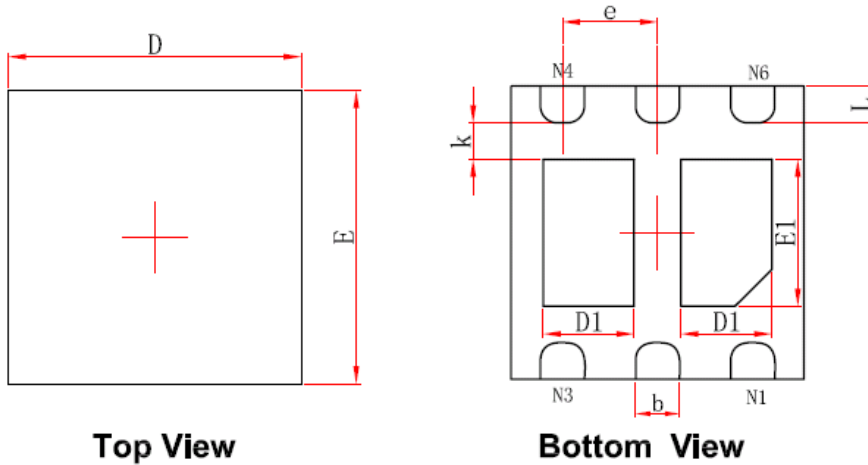
Parameter: Thermal Characteristics MOSFET	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$t \leq 10s$	$R_{\theta JA}$	86	$^\circ C/W$

Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise note)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = -250uA, V <sub>GS</sub> =0V	-20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V			-1	uA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±12V			±100	nA
V <sub>GS(IN)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-0.6	-0.85	-1.4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -4.7A		48	60	mΩ
		V <sub>GS</sub> = -2.7V, I <sub>D</sub> = -3.8A		63	90	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -1.0A		65	100	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.7A		8.0		S
<b>DYNAMIC PARAMETERS</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -6V, f= 1MHz		415		pF
C <sub>OSS</sub>	Output Capacitance			223		pF
C <sub>RSS</sub>	Reverse Transfer Capacitance			87		pF
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-10V, I <sub>D</sub> = -4.7A		24	36	nC
Q <sub>gs</sub>	Gate Source Charge			18		nC
Q <sub>gd</sub>	Gate Drain Charge			2.7		nC
T <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> =-1A, R <sub>GEN</sub> =6Ω		22	35	ns
t <sub>r</sub>	Turn-On Rise Time			35	55	ns
T <sub>D(off)</sub>	Turn-Off DelayTime			45	70	ns
t <sub>f</sub>	Turn-Off Fall Time			25	40	ns
I <sub>s</sub>	Max. Diode Forward Current				-1.7	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> =-1.7A			-1.2	V

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



DFNWB2×2-6L-A (P0. 65T0. 75/0. 85) PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.520	0.720	0.020	0.028
E1	0.900	1.100	0.035	0.043
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013

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